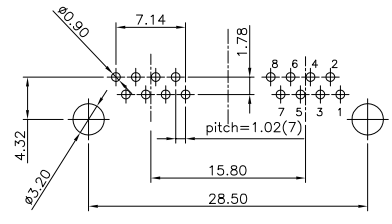
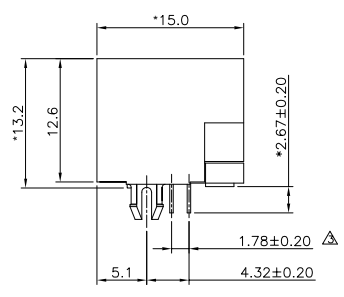
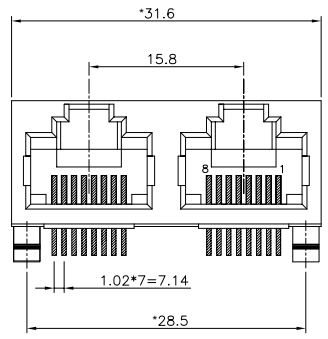


D1RFRD006

REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD
△		P/N MODIFY	Jake 12/07/04	
△		P/N MODIFY	Yuan 12/16/04	
△		DIMENSION MODIFY	Yuan 08/08/05	



PC Board Layout T=1.60mm
Component Side Shown

NOTES:

ELECTRICAL:

- VOLTAGE RATING : 125 VAC RMS.
- CURRENT RATING : 1.5 AMP.
- CONTACT RESISTANCE : 30 MILLIOHMS MAX.
- INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
- DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.
- OPERATING: 750 CYCLES MIN.

MECHANICAL:

- HOUSING MATERIAL : NYLON+30%.G.F(FR52) UL94V-0.COLOR-BLACK.
- INSERT MATERIAL : NYLON+30%.G.F(FR52) UL94V-0.COLOR-BLACK.
- BACK PLATE MATERIAL : NYLON+30%.G.F(FR52) UL94V-0.COLOR-BLACK.
- CONTACT MATERIAL : PHOSPHOR BRONZE 0.35mm THICKNESS OR 0.46mm.
- PLATING : GOLD PLATING OVER NICKEL.
- PCB RETENTION PRE-SOLDER : 1 LB MIN.
- PCB RETENTION POST-SOLDER: 10 LBS MIN.

ENVIRONMENTAL:

- STORAGE : -40°C TO +85°C.
- OPERATION: -40°C TO +85°C.
- WAVE SOLDERING TEMPERATURE: 255~265°C (5~10 SECONDS)

MATES WITH MODULAR PLUG CONFORMING TO
FCC PART 68, SUBPART F.
CUL FILE NO. E163191

△ PART NUMBER: E5J88- 0 0 A J X X-L △
G-STAMPED PIN. _____ PLATING:1-3u",
H-ROUND PIN _____ 2-6u",
3-15u",
4-30u",
5-50u"

<p>MM (INCH)</p> <p>TOLERANCES EXCEPT AS NOTED</p> <p>mm ±</p> <p>.0 ±0.20 ±</p> <p>.00 ±0.15 ±</p> <p>.000 ±0.075 ±</p>		<p>DFTO Jake DATE 05/05/04</p> <p>CHKD Chi DATE 08/08/05</p> <p>MFO Tzou DATE 08/08/05</p> <p>APPLV Yuan DATE 08/08/05</p> <p>MATERIAL :</p>	<p>FULL RISE ELECTRONIC CO., LTD</p> <p>TITLE ROHS LED GANG JACK 2 PORTS</p> <p>DRAWING NO. GESJ3T38 SIZE REV /PART NO. SEE NOTE A3 3</p>
<p>ANGLES ±</p> <p>THIRD ANGLE PROJECTION</p>	<p>QTY :</p> <p>FINISH :</p> <p>SCALE : 50:19</p>	<p>DO NOT SCALE DRAWING</p> <p>SHEET 1 OF 1</p>	

8 | 7 | 6 | 5 | 4 | 3 | 2 | 1

H
G
F
E
D
C
B
A